

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Renesas Electronics Corportion	02/15/2024
RECEIVING PARTY DATA	
Company Name:	SONY GROUP CORPORATION
Street Address:	1-7-1 Konan
Internal Address:	Minato-ku
City:	Tokyo, 108-0075
State/Country:	JAPAN
PROPERTY NUMBERS Total: 2	
Property Type	Number
Application Number:	12588392
Application Number:	15955819
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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NAME OF SUBMITTER:	MRS. JENNINGS Christine
SIGNATURE:	MRS. JENNINGS Christine
DATE SIGNED:	04/08/2024
Total Attachments: 3	
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PATENT ASSIGNMENT

This PATENT ASSIGNMENT, effective as of the date last signed hereto, is made by and between Renesas Electronics Corporation (hereinafter "Assignor") and Sony Group Corporation (hereinafter "Assignee").

WHEREAS:

Assignor is the sole owner of the patents listed in the attached Exhibit A (hereinafter "Patents"); and

Assignee is desirous of acquiring all of Assignor's right, title and interest in and to the Patents.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound hereby, Assignor does hereby sell, assign and transfer to Assignee the entire right, title and interest in and to any and all of the following:


- (i) the Patents, including any and all inventions, invention disclosures, improvements and discoveries disclosed or claimed therein (hereinafter "Inventions"), for the United States, its possessions and territories and all foreign countries, regions and territories;
- (ii) the rights of priority created by the Patents under any treaty relating thereto, including the rights to apply for patents and patent applications covering the Inventions in any and all countries, regions and territories;
- (iii) any and all patents and patent applications, certificates of invention, utility models and any other grants by any governmental entity for the protection of inventions resulting from the Patents, in any and all countries, regions and territories, including any and all patents and patent applications disclosing the Inventions and any patents issuing from such applications, including provisionals, non-provisionals, divisionals, continuations, continuations-in-part, reissues, extensions, renewals, substitutions and re-examinations of the Patents; and
- (iv) all past, present and future causes of action and enforcement rights, whether currently pending, filed or otherwise, in connection with the Patents, the patents and patent applications resulting from the Patents and the Inventions, including without limitation, all rights to sue for any past, present or future infringement thereof, including the rights to license and to collect and receive any damages, royalties, injunctive relief, and/or any other settlements or remedies for such infringements, and including any provisional rights having arisen from any publication of any of the Patents or any patent application resulting therefrom,

the same to be held and enjoyed by Assignee for its own use and enjoyment, and for the use and enjoyment of its successors, assigns and other legal representatives, as fully and entirely as the same would have been held and enjoyed by Assignor, if this Assignment and sale had not been made.

AND, this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment.

IN WITNESS WHEREOF, Assignor and Assignee, by and through their respective authorized representative, have executed this instrument on the date indicated below.

SIGNED for and on behalf of Assignor

By		2024年2月15日
	_____ (Signature)	_____ (Date)
	Yasushi Adachi (Print Name)	Director, Patent Department, Legal Division (Print Title)

SIGNED for and on behalf of Assignee

By	<u>Shizuka Sayama</u> <small>Shizuka Sayama (2024年2月15日 12:04 GMT+9)</small>	2024年2月15日
	_____ (Signature)	_____ (Date)
	Shizuka Sayama (Print Name)	General Manager, IP Alliance and Licensing Department Intellectual Property and Standards Division (Print Title)

EXHIBIT A

Country	Application No.	Patent or Publication No.	Filing date	Title
US	12/588,392	8,183,645	Oct.14,2009	Power semiconductor device including gate lead-out electrode
US	15/955,819	10,361,189	Apr.18,2018	Semiconductor device and manufacturing method thereof